

LL4148 Small Signal Diode



COLOR BAND MARKING

1ST BAND
Black
Green

Absolute Maximum Ratings * $T_a = 25$ °C unless otherwise noted

Symbol	Parameter	Value	Unit	
V _{RRM}	Maximum Repetitive Reverse Voltage	100	V	
I _{F(AV)}	Average Rectified Forward Current	200	mA	
I _{FSM}	Non-repetitive Peak Forward Surge Current Pulse Width = 1.0 second Pulse Width = 1.0 microsecond		A A	
T _{STG}	Storage Temperature Range -65 to +200 °C		°C	
TJ	Operating Junction Temperature 175		°C	

 $^{^{\}star}$ These ratings are limiting values above which the serviceability of the diode may be impaired.

Notes

Thermal Characteristics

Symbol	Parameter	Value	Unit
P_{D}	Power Dissipation	500	mW
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient	300	°C/W

Note: Jedec Standard 51-3 method(PCB Board size 76*114*0.6Tmm³)

Electrical Characteristics T_C = 25°C unless otherwise noted

Symbol	Parameter	Conditions	Min.	Max.	Units
V _R	Breakdown Voltage	$I_R = 100 \mu A$ $I_R = 5.0 \mu A$	100 75		V V
V _F	Forward Voltage	I _F = 10mA		1.0	V
I _R	Reverse Leakage	V _R = 20V V _R = 20V, T _A = 150°C		25 50	nA μA
C _T	Total Capacitance	V _R = 0, f = 1.0MHz		4.0	pF
t _{rr}	Reverse Recovery Time	$I_F = 10 \text{mA}, V_R = 6.0 \text{V (60mA)},$ $I_{rr} = 1.0 \text{mA}, R_L = 100 \Omega$		4.0	ns

Package Marking and Ordering Information

Device Marking	Device	Package	Reel Size	Tape Width	Quantity
Color Band Marking	LL4148	SOD80	7"	8mm	2,500

¹⁾ These ratings are based on a maximum junction temperature of 200 degrees ${\sf C}.$

²⁾ These are steady state limits. The factory should be consulted on applications involving pulsed or low duty cycle operations.

Typical Performance Characteristics

Figure 1. Reverse Voltage vs Reverse Current BV - 1.0 to $100\mu A$

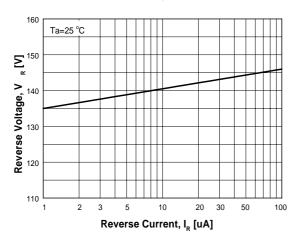


Figure 3. Forward Voltage vs Forward Current V_F - 1 to $100 \mu A$

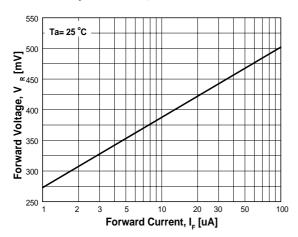


Figure 5. Forward Voltage vs Forward Current V_F - 10 to 800mA

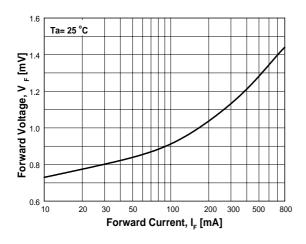


Figure 2. Reverse Voltage vs Reverse Current I_R - 10 to 100V

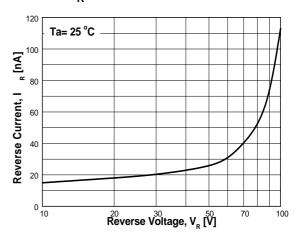


Figure 4. Forward Voltage vs Forward Current V_{F} - 0.1 to 10mA

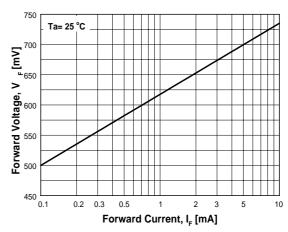
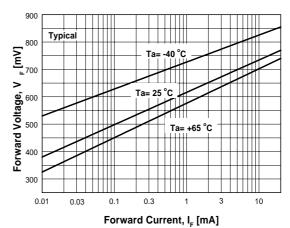


Figure 6. Forward Voltage vs
Ambient Temperature
V_F - 0.01 - 20mA (-40 to +65 Deg C)



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Typical Performance Characteristics

Figure 7. Total Capacitance

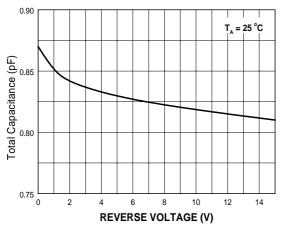


Figure 9. Average Rectified Current $(I_{F(AV)})$ versus Ambient Temperature (T_A)

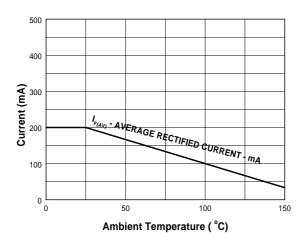


Figure 8. Reverse Recovery Time vs Reverse Recovery Current

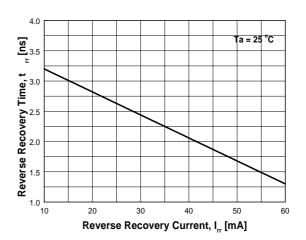
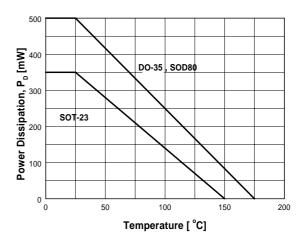
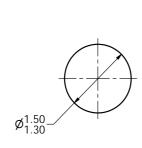


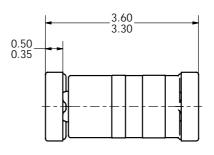
Figure 10. Power Derating Curve



Mechanical Dimensions

SOD80





NOTE/s:

- 1) THIS PACKAGE CONFORMS TO JEDEC DO-213D, VARIATION AC, DATED 9/1988. 2) ALL DIMENSIONS ARE IN MILLIMETERS.

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